Sony Chemical & Information Device Corporation

Technical Data Sheet

Strong adhesive type double coated tapes UT1400 series

Features

Structure

- Adhesive tape with lower environmental impact with UV curable manufacturing method (non solvent adhesive coating process).
- It has the adhesive power about twice G series (compared with our company), and it is suitable for bonding on glass and a metallic side.
- It contributes to the diversification of the product design because it is excellent in the static load characteristic (practical characteristic) such as Curved surface bending and Stable weight peeling.
- It is possible to excel in heatproof, and to use it under the environment of 120°C.

	Adhesive Nonwoven fabric Adhesive Release paper	Product name	UT1430	UT1440	
		Main component	Acrylic	Acrylic	
		Carrier	Nonwoven fabric	Nonwoven fabric	
		Color	Translucent	Translucent	
		Adhesive thickness (μ m)	About 300	About 400	
		Release paper thickness (μ m)	About 140	About 140	
		Bonding strength (N/20mm) *	32	33	
		St'd size (width & length)	480mm × 50m	480mm × 50m	

Suitable use

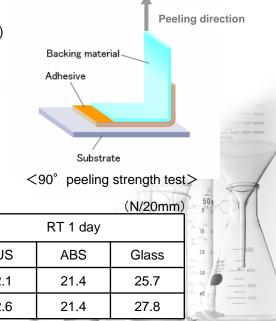
90° peeling strength

■ Ideal for plastics and metals for front panels and glasses for scanners.

Technical data

1. Bonding strength on various type of substrate (90° peeling)

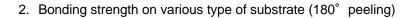
<Test piece condition> Tape width: 20mm Bonding condition: One stroke with 2-kg roller Measuring condition: $23^{\circ}C \pm 5^{\circ}C 60\% \pm 20\%$ RH Peeling speed: 300mm/min Backing material: 40μ m Aluminum foil [Left at RT for one hour / one day before measurement]



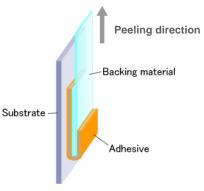
TDS-021

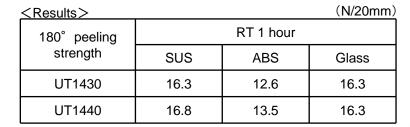
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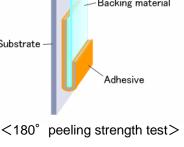
							(=0		
90° peeling			RT 1 hour			RT 1 day		n n	
	strength	SUS	ABS	Glass	SUS	ABS	Glass	20	
	UT1430	23.5	18.4	22.7	32.1	21.4	25.7		
	UT1440	25.1	19.7	23.0	32.6	21.4	27.8		



<Test piece condition> Tape width: 20mm Bonding condition: One stroke with 2-kg roller Measuring condition: 23°C±5°C 60%±20%RH Peeling speed: 300mm/min Backing material: 25μ mPET [Left at RT for one hour before measurement]







Adhesive

Backing material

Substrate

3. Holding power at different temperatures

<Test piece condition> Substrate: Stainless steel plate (SUS304) Bonding area: 25mm × 25mm Bonding condition: One stroke with 2-kg roller [Left at RT for one hour and then at each temperature for 30 minutes before measurement] [Creep length after one hour application of 1-kg load]

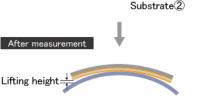
<Results>

Measurement temperature	Creep length (mm)			
	80°C	120°C		
UT1430	0.7	1.2		
UT1440	0.9	1.4		

4. Curved surface bending

<Test piece condition> Substrate ①: Aluminum plate 0.5mm × 20mm × 150mm Substrate 2: ABS plate 2mm × 25mm × 200mm Bonding condition: One stroke with 2-kg roller Measuring condition: 50°C [Left at RT for 24 hours, then lifting height of the edge after the elapsed time is measured]

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Weight 1kg
<holding power="" test=""></holding>
Before measurement
Substrate① Adhesive
Substrate2



Measure the lifting height after bending < Curved surface bending test >

<Results>

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Measurement temperature		Product name	1 hour	3 hours	5 hours	8 hours	24 hours
Lifting height	Lifting height ABS/AL	UT1430	0	0	0	0	1.5
(mm)	AD5/AL	UT1440	0	0	0	0	0

Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used. Revision in Oct, 2010

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